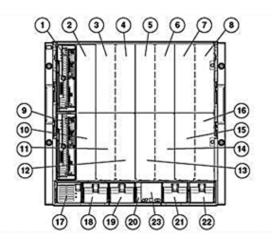
QuickSpecs

Overview

HPE BladeSystem c7000 Enclosure and Server Blades - Carrier Grade Supplement



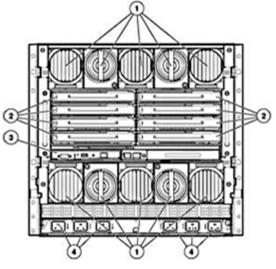


- 1. Device Bay 1
- 2. Device Bay 2
- 3. Device Bay 3
- 4. Device Bay 4
- 5. Device Bay 5
- 6. Device Bay 6
- 7. Device Bay 7
- 8. Device Bay 8
- 9. Device Bay 9
- 10. Device Bay 9
- 11. Device Bay 11
- 12. Device Bay 12
- 13. Device Bay 13
- 14. Device Bay 14
- 15. Device Bay 15
- 16. Device Bay 16
- 17. Power Supply Bay 1
- 18. Power Supply Bay 2
- 19. Power Supply Bay 3
- 20. Power Supply Bay 4
- 21. Power Supply Bay 5
- 22. Power Supply Bay 6
- 23. Insight Display

Hewlett Packard Enterprise



- 1. Active Cool 200 Fans & fan bays
- 2. Interconnect Bays
- 3. Onboard Administrator
- 4. Power Inputs



Overview

At A Glance

This document covers the NEBS Level 3 certified HPE BladeSystem c7000 Enclosure. This document covers the blades, interconnects, etc. which have passed the NEBS Level 3 and ETSI EN 300 386-2 certifications. Testing and certification is limited to - 48VDC powered enclosures. For more information on HPE ProLiant Server Blades and HPE BladeSystem c-Class Interconnect Components please see the following QuickSpecs:

- HPE ProLiant c-Class Server Blades:
 https://www.hpe.com/us/en/integrated-systems/bladesystem.html
- HPE BladeSystem c-Class Interconnect: <u>https://www.hpe.com/h20195/v2/GetDocument.aspx?docname=4AA0-5964ENW</u>
- HPE BladeSystem c3000 Enclosure QuickSpecs: https://www.hpe.com/h20195/v2/GetDocument.aspx?docname=c04123379

HPE BladeSystem Carrier Grade (CG) solutions start with a BladeSystem c7000 Enclosure, c7000 hot-plug -48VDC power supplies, HPE Active Cool Fans, and an optional redundant Onboard Administrator module. Once the enclosure has been selected, the following components can be added: networking interconnect modules, HPE ProLiant and Integrity Server Blades, and Insight Control management software. Reference the QuickSpecs listed above.

- Warranty This product is covered by a global limited warranty and supported by HPE Services and a worldwide network of Hewlett Packard Enterprise Authorized Channel Partners. Hardware diagnostic support and repair is available for three years from date of purchase. Support for software and initial setup is available for 90 days from date of purchase. Additional support may be covered under the warranty or available for an additional fee. Enhancements to warranty services are available through HPE Care Pack services or customized service agreements.
- Enclosure: Three-year parts and labor, on-site limited global warranty. Certain restrictions and exclusions apply
- Enclosure options: Fans, Power Supplies, Onboard Administrator, 1 Year parts only or enclosure warranty
- HPE BladeSystem Interconnects: 1 Year parts and labor, on-site regardless of the warranty period for the system in which they are installed
- **HPE Storage Fibre Channel switches:** have a maximum warranty period of one (1) year regardless of the warranty period for the system in which they are installed
- SATA hard drives have a one year parts and labor on-site warranty regardless of the system in which they are installed
- **SAS Enterprise drives** have a 3 year warranty regardless of the system in which they are installed.

For additional information please visit: http://www.hpe.com/info/bladesystem

HPE BladeSystemA BladeSystem c7000 enclosure holds up to 16 server and/or storage blades plus redundant network and
storage switches. It includes a shared, multi-terabit high-speed mid-plane for wire-once connectivity of server
blades to network and shared storage. Power is delivered through a pooled power backplane that ensures the
full capacity of the redundant hot-plug power supplies is available to all blades.

Each c7000 Carrier Grade enclosure is built with the following functions:

- Up to 16 half-height and/or up to 8 full-height server blades and/or storage blades per enclosure.
- Up to 4 different interconnect fabrics (Ethernet, FC) supported simultaneously within the enclosure.
- -48V DC power subsystem .
- HPE Thermal Logic technology for lower power consumption and airflow.
- Ten (10) Active Cool 200 fans required for Telco operation

Overview

- Redundant hot-plug cooling, redundant hot-plug power supplies, redundant connections, redundant interconnect modules, optional redundant Onboard Administrator management modules.
- Lowest cost of ownership.

An Onboard Administrator management module is built into the enclosure with the following functions:

- Robust, multiple enclosure setup and control.
- Reports asset and inventory information for the devices in the enclosure.
- Reports thermal and power information, including real-time actual power usage per server and per enclosure.
- Front-mounted Insight Display for easy management within the datacenter.
- Integrated access to all server blade iLOs from a single cable.
- Provides integrated access to interconnect bay device management ports from the single Onboard Administrator cable.
- Single sign-on capability for all devices in the enclosure
- Role-based security locally and/or with LDAP directory services.
- Provides a wizard-based initial setup process for easy configuration.

A BladeSystem c7000 enclosure provides the following benefits:

- With local and remote hardware management integrated across the solution, one full enclosure can be managed as easily as one server.
- Scalable: Management and network interconnects extend scalability beyond a single enclosure, allowing resources to be pooled and shared across multiple enclosures.
- Investment protection: Accommodates multiple server and network designs in one enclosure.
- Lower costs per server, in comparison to rack-mounted servers
- Lower power consumption, in comparison to rack-mounted servers.
- Lower airflow requirements, in comparison to rack-mounted servers

HPE ProLiant &
Integrity ServerDelivering best-in-class performance, choice and reliability on Intel® Xeon® and Intel® Itanium 2® processors for
Windows, Linux, Solaris, or HP-UX based servers; the HPE portfolio of server blades supports a variety of
application requirements for scale-out architectures. The HPE BL460c Gen8 and BL860i2 have been certified
as NEBS Level 3.

For more information please see: https://www.hpe.com/us/en/integrated-systems/bladesystem.html

Configuration Information - Factory Integrated Models

NOTE: For a complete configuration of the HPE BladeSystem, please do the following:

Step 1: Select desired model, configuration and quantity of HPE ProLiant server

NOTE: For server blade information, please visit: https://www.hpe.com/us/en/integrated-systems/bladesystem.html

Step 2: Determine quantity of HPE BladeSystem c-Class Enclosures to purchase and choose Required Options (One of the following from each list unless otherwise noted):

NOTE: Each HPE BladeSystem c-Class Server Blade Enclosure holds up to 16 half-height blades. Server blanks will be shipped in all empty bays.

Base Server Blade Enclosure Configuration

HPE	HP Integrity BLc7000 CTO Enclosure	AD361D		
BladeSystem	System HP BLc7000 Platinum Configure-to-order Enclosure with ROHS Trial IC Lic			
BLc7000 c-Class Server Blade Enclosures	NOTE: CTO models include 1x Onboard Administrator with KVM, 4x Active Cool 200 Fans and 0x power supplies. NOTE: The AD361D enclosure is suggested for configurations primarily used with Integrity blades.			

Required Options (one of the following from each category unless otherwise noted)

c-Class Power Modules (1 per enclosure)	HP BLc7000 -48V DC Power Input Module	AH331A
c-Class Power Supply (Up to 6)	HPE 2250W Performance -48VDC Hot Plug Power Supply Kit NOTE: Only compatible with -48V DC Power Input Module. HPE 2650W Performance -48VDC Platinum Hot Plug Power Supply Kit NOTE: This power supply kit disables HPE Power Discovery Services. NOTE: Compatible with the HPE BLc7000 -48V DC Power Input Module AH331A. See the "c- Class Power Modules" section above for the power modules.	AH332A 789934-B21
	HPE 6X 2650W Performance -48VDC Hot Plug FIO Power Supply Kit NOTE: This power supply kit disables HPE Power Discovery Services. NOTE: Compatible with the HPE BLc7000 -48V DC Power Input Module AH331A. See the "c- Class Power Modules" section above for the power modules. NOTE: Includes a quantity of 6 2650W -48VDC power supplies so a full enclosure can be configured with a single part number.	789935-B21
c-Class Active Cool Fan (Up to 6)	HP BLc 6X Active Cool 200 Factory Integrated Fan Option NOTE: The bundle includes a quantity of 6 HPE Active Cool 200 Fans so a full enclosure can be configured with a single part number. NOTE: NEBS Level 3 certification requires 10 fans.	517520-B21

Configuration Information - Factory Integrated Models

Step 3: Select an optional software bundle (if nothing is selected the enclosure will ship with 16 Insight Control Trial Licenses):

 HPE Insight
 HPE Insight Control for BladeSystem including 1yr 24x7 Support Enclosure 8-server FIO E-LTU
 C6N32ABE

 Software
 NOTE: This license supports HPE ProLiant c-Class blade servers.
 NOTE: Must be purchased as an option to an HPE BladeSystem enclosure. FIO can only be ordered as part of a factory-configured platform. Customer will receive a printed license entitlement certificate via physical shipment.

Step 4: Select optional Redundant Onboard Administrator Capability

BL c-Class	HP BLc7000 Onboard Administrator with KVM Option		
Infrastructure	NOTE: Models of the c7000 enclosure (part numbers 507019-B21 and AD361C) come with an		
	Onboard Administrator with KVM as standard. Order this part number (456204-B21) when a		
	second redundant Onboard Administrator is desired for a c7000 enclosure.		

Step 5: Select 1 or more interconnect modules for each enclosure

The following is a list of various HPE BladeSystem c-Class interconnect modules (Virtual Connect, Ethernet, and Fibre Channel), which have been tested for NEBS Level 3 compliance. For detailed interconnect options consult the specific interconnect QuickSpecs: http://h18004.www1.hp.com/products/blades/components/c-class-interconnects.html

A pair of interconnects must be ordered if redundancy is required.

NOTE: Options for specific c-Class interconnects are NOT included in the list below. Consult the individual interconnect QuickSpecs to obtain part numbers for interconnect options such as cables, SFPs, etc.

HPE	HP Virtual Connect Flex-10/10D Module for c-Class BladeSystem	638526-B21
BladeSystem	HP Virtual Connect FlexFabric-20/40 F8 Module for c-Class BladeSystem	691367-B21
c-Class Network	HP Virtual Connect FlexFabric-20/40 F8 Module for c-Class BladeSystem with TAA	691367-B22
Interconnects	HP Virtual Connect FlexFabric 10/24 Enterprise Edition BLc7000 Option	605865-B21
	HP Virtual Connect FlexFabric 10Gb/24-port Module for c-Class BladeSystem	571956-B21
	HPE 6127XLG Ethernet Blade Switch	737685-B21
	HP 6127XLG Ethernet Blade Switch for TAA	787635-B22
	HP 6125G Ethernet Blade Switch	658247-B21
	HP 6125G/XG Ethernet Blade Switch	658250-B21
	HP 6120XG Blade Switch	516733-B21
	Mellanox SX1018HP Ethernet Switch for c-Class BladeSystem	689638-B21
	HP 10GbE Ethernet Pass-Thru Module for c-Class BladeSystem	538113-B21
	HP 1GB Ethernet Pass-Thru Module for c-Class BladeSystem	406740-B21
	HP 4GB Fibre Channel Pass-thru Module for c-Class BladeSystem	403626-B21

Configuration Information - Factory Integrated Models

	HP Virtual Connect 8Gb 24-port Fibre Channel Module for c-Class BladeSystem	466482-B21
	Brocade 16Gb/16 SAN Switch for BladeSystem c-Class	C8S45A
	Brocade 16Gb/28 SAN Switch for BladeSystem c-Class	C8S46A
	Brocade 16Gb/28 SAN Switch Power Pack+ for BladeSystem c-Class	C8S47A
	Brocade 8/12c SAN Switch for BladeSystem c-Class	AJ820B
	Brocade 8/24c Power Pack+ SAN Switch for BladeSystem c-Class	AJ822B
HPE	Brocade 8/24c SAN Switch for BladeSystem c-Class	AJ821B
BladeSystem	HPE Brocade 8/12c SAN Switch Upgrade LTU	A5517B
c-Class SAN	Brocade 8/24c SAN Switch for BladeSystem c-Class	AJ821B
Interconnect	Brocade 8/24c SAN Switch for BladeSystem c-Class	AJ821B
HPE	HP 4X FDR InfiniBand Managed Switch Module for c-Class BladeSystem	648311-B21
BladeSystem	HP 4X FDR InfiniBand Switch Module for c-Class BladeSystem	648312-B21
Infiniband	NOTE: The HPE BLc FDR IB Switches are only supported on the HPE BladeSystem c7000	
Interconnect	Enclosures P/N's: 681840-B21, 681842-B21, 681844-B21, 507014-B21, 507015-B21, 507016-B21,	
	507017-B21 and 507019-B21.	
	NOTE: Please see the HPE BladeSystem c7000 Enclosure QuickSpecs for additional	
	information at: https://www.hpe.com/h20195/v2/GetDocument.aspx?docname=c04229580	
	(Worldwide)	
c7000 Enclosure	HP BLc7000 Onboard Administrator with KVM Option	456204-B21
Options	NOTE: Models of the c7000 enclosure (P/Ns 507019-B21: 507015-B21, 507017-B21, 507016-	
	B21, 507014-B21) come with an Onboard Administrator with KVM as standard. Order (P/N	
	456204-B21) when a second redundant Onboard Administrator is desired for a c7000	
	enclosure.	
	HP BLc7000 10000 Series Rack Shipping Bracket Option	433718-B21
	NOTE: The shipping bracket is required for shipping a c7000 enclosure when installed in a HPE 10000 G2 rack. It is not required for normal operation.	
	HP c-Class BladeSystem Miscellaneous Blanks Option Kit	412148-B21
	NOTE: This kit should only be ordered to replace lost or damaged blanks.	
	HP c-Class BladeSystem Bay Blank with Coupler Option	412150-B21
	NOTE: The coupler allows half-height server blanks to be coupled together to create a full-	
	height server blank.	
	NOTE: This kit should only be ordered to replace lost or damaged blanks.	

Step 6: Select NEBS certified server blades

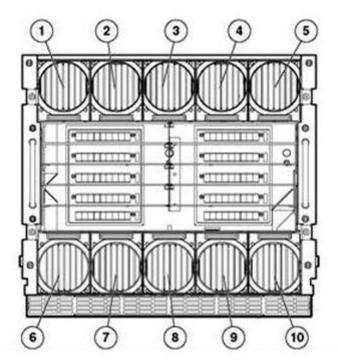
HPE Proliant	HP ProLiant BL460c Gen9 E5-v3 10Gb/20Gb FlexibleLOM Configure-to-order Blade Server	727021-B21
Blade Server	Configurable Model Ships with:	
	One (1) FlexibleLOM connector providing a choice for one (1) of the supported 10Gb/20Gb	

FlexibleLOMs	
Two (2) HPE small form factor hot-plug SAS/SATA/ HDD or SSD hard drive bays Two (2) x16 PCIe I/O expansion slots One (1) integrated USB connector and one (1) MicroSDHC connector One (1) TPM connector HPE iLO Management (standard)	
HP BLc PCI Expansion Blade NOTE: Please see the QuickSpecs for Technical Specifications and additional information: <u>https://www.hpe.com/h20195/v2/GetDocument.aspx?docname=c04123380</u>	448018-B21
HP 36U 1M Seismic Rack	AH343A
HP c7000 Enclosure Seismic Kit HP Seismic Cabinet Caster Kit HP Seismic Cabinet Concrete Anchor HP Seismic Cabinet Raised Floor Anchor HP BladeSystem Breaker Panel HP BladeSystem c-Class 2.0m Breaker Panel Power Cable HP BladeSystem c-Class 1.3m Breaker Panel Power Cable HP BLc 30 Ampture Breaker Option	AH330A AH336A AH334A AH335A AH355A AH392A AH393A AM336A
	Two (2) x16 PCIe I/O expansion slots One (1) integrated USB connector and one (1) MicroSDHC connector One (1) TPM connector HPE iLO Management (standard) HP BLc PCI Expansion Blade NOTE: Please see the QuickSpecs for Technical Specifications and additional information: https://www.hpe.com/h20195/v2/GetDocument.aspx?docname=c04123380 HP 36U 1M Seismic Rack HP c7000 Enclosure Seismic Kit HP Seismic Cabinet Caster Kit HP Seismic Cabinet Concrete Anchor HP Seismic Cabinet Raised Floor Anchor HP BladeSystem Breaker Panel HP BladeSystem c-Class 2.0m Breaker Panel Power Cable HP BladeSystem c-Class 1.3m Breaker Panel Power Cable

Fan Bay and Device Bay Numbering and Population Guidelines

Server Blade and Fan Population Guidelines

Fan bay numbering

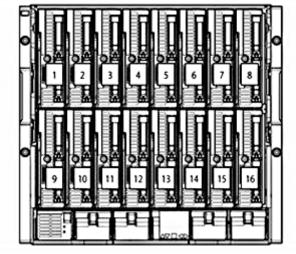


Fans must be placed in the following bays

4, 5, 9, 10
6 3, 4, 5, 8, 9, 10
8 1, 2, 4, 5, 6, 7, 9, 10
10 1, 2, 3, 4, 5, 6, 7, 8, 9, 10

NOTE: For correct operation fans and server blades must be installed in the correct bays. The Onboard Administrator will ensure that fans and blades are correctly placed before allowing systems to power on.

Fan Bay and Device Bay Numbering and Population Guidelines



Half-height server blade bay numbering

1. Device Bay 1

2. Device Bay 2

3. Device Bay 3

4. Device Bay 4

5. Device Bay 5

6. Device Bay 6

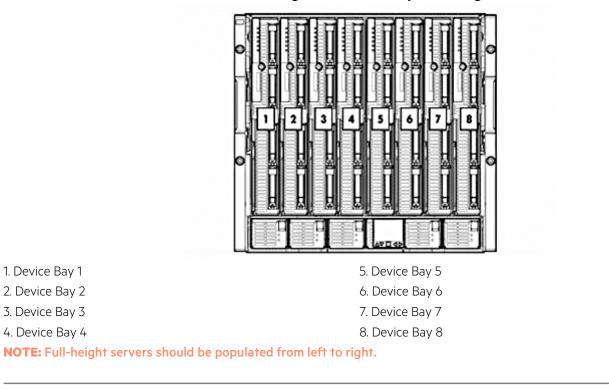
7. Device Bay 7

8. Device Bay 8

9. Device Bay 9
10. Device Bay 10
11. Device Bay 11
12. Device Bay 12
13. Device Bay 13
14. Device Bay 14
15. Device Bay 15
16. Device Bay 16

NOTE: Half-height servers should be populated from top and bottom from left to right from the front of the enclosure. So the first two half-height servers would be placed in bays 1 & 9 the second two half-height servers would be placed in bays 2 & 10 and so on until the enclosure is full.

Fan Bay and Device Bay Numbering and Population Guidelines



Full-height server blade bay numbering

Blade Blade Blade Zone 3 Blade Zone 4

The c7000 enclosure is divided into 4 quadrants by the vertical support metalwork. Within each quadrant a removable divider is used to support half height devices. To install a full-height blade in any quadrant this divider must be removed. As a consequence a quadrant can only contain either full-height server blades or half-height server blades.

NOTE: Storage blades and Tape blades can be installed in the same quadrant as both full-height and half-height blades, a bracket ships with each SB40c/Tape Blade that allows a half-height blade to be mounted on top of the storage blade. **NOTE:** The lower tape or storage blade cannot be removed without first removing the upper half height blade.

Mixed Configuration - Full Height and Half-Height Population rules

Technical Specifications

HPE BladeSystem	Dimensions	Height	17.4 in (442 mm)
c7000 Server		Width	17.6 in (447.04 mm)
Blade Enclosurex		Depth	36.4 in (925 mm)
	Shipping Dimensions	Height	29.88 in (759 mm)
		Width	23.88 in (607 mm)
		Depth	39.88 in (1013 mm)
	DC Input Enclosure	Unboxed	151 lb (68.5 Kg)
	Weight	Shipping	194 lb (88 Kg)
	Max Enclosure	Unboxed	450 lb (204 Kg)
	Weight	Shipping	493 lb (223.6 Kg)
	(approximate)	Shipping	475 10 (225.0 Kg)
	Temperature Range	Operating	50° to 95° F (10° to 35° C)
		Non-Operating	-22° to 140° F (-30° to 60° C)
	Relative Humidity	Operating	10 to 90% relative humidity (Rh), 28°C (82.4°F)
	Kelanve namany	operating	maximum wet bulb temperature, non-condensing.
		Non-Operating	5 to 95% relative humidity (Rh), 38.7°C
			(101.7°F)maximum wet bulb temperature, non-
			condensing.
			ing of 1.8° F (1° C) per 1,000 ft (304.8 m). No direct
	sunlight. Upper operat	ting limit is 10,000 ft (3,048 m	n) or 70Kpa/10.1 psia. Upper non-operating limit is

sunlight. Upper operating limit is 10,000 ft (3,048 m) or 70Kpa/10.1 psia. Upper non-operating limit is 30,000 ft (9,144 m) or 30.3 KPa/4.4 psia. Storage maximum humidity of 95% is based on a maximum temperature of 113° F (45° C). Altitude maximum for storage is 70 KPa.

Power	Input Requirements	Rated Input Voltage	-36 to -72 VDC
	DC Power	Max Input Current per line cord	75A
		Max Input Power per line Cord	2700W
		-48V DC Power	Terminal lug: 45DG 4 AWG ¼ 2H Two-hole lug 45 degree bend 0.25in. (6.4mm) stud hole size 0.63in. (16mm) hole spacing
	Output Specifications (per power supply)	HPE 2250W -48V DC Hot-Plug Power Supply	2250W
	Acoustic Noise	Listed are the declared A-Weig	hted sound power levels (LWAd) and declared average

Technical Specifications

		bystander position A-Weighted sound pressure levels (LpAm) when the product is operating in a 23°C ambient environment. Noise emissions were measured in accordance with ISO 7779 (ECMA 74) and declared in accordance with ISO 9296 (ECMA 109).		
		Idle		
			LWAd	7.1 Bels
			LpAm	54 dB
		Idle		
			LWAd	7.2 Bels
			LpAm	54 dB
Option Kits	Power Supply Option	Height		8.75 in (223 mm)
	Shipping Dimensions	Width		8.63 in (219 mm)
		Depth		35.13 in (892 mm)
		Weight		8.5 lbs (3.85 Kg)
	Fan Option Shipping	Height		8.75 in (223 mm)
		Width		9.75 in (248 mm)
		Depth		15.88 in (403 mm)
		Weight		4.0 lbs (1.8 Kg)
	Onboard	Height		2.50 in (63.5 mm)
	Administrator	Width		9.88 in (251 mm)
	Option Shipping Dimensions	Depth		13.50 in (343 mm)
	Dimensions	Weight		4.0 lbs (1.8 Kg)
Environment- friendly Products and Approach	End-of-life Management and Recycling	Hewlett Packard Enterprise offers end-of-life Hewlett Packard Enterprise product return, trade-in, and recycling programs in many geographic areas. For trade-in information, please go to: http://www.hpe.com/info/recycle. To recycle your product, please go to: http://www.hpe.com/info/recycle or contact your nearest Hewlett Packard Enterprise sales office. Products returned to Hewlett Packard Enterprise will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard Enterprise web site at: http://www.hpe.com/info/recycle. These instructions may be used by recyclers and other WEEE treatment facilities as well as HEWLETT PACKARD ENTERPRISE OEM customers who integrate and re-sell Hewlett Packard Enterprise equipment.		

Power Specifications

NOTE: To review maximum system power ratings for facilities planning purposes use the Active Answers Power Calculator which is available via the online tool located at URL:

https://www.hpe.com/us/en/integrated-systems/rack-power-cooling.html#Portfolio

Summary of Changes

Date	Version History	Action	Description of Change
05-Jul-2016	From Version 19 to 20	Changed	Overview, Configuration Information - Factory Integrated Models, and
			Technical Specifications sections were updated.
		Added	SKUs added in Configuration Information – Factory Integrated Models:
			789934-B21, 789935-B21, 727021-B21.
		Removed	SKUs removed from QuickSpecs:
			735151-B21, 679118-B21.
11-Mar-2016	From Version 18 to 19	Changed	Configuration Information - Factory Integrated Models section was
			updated.
		Added	SKUs added to QuickSpecs:
			691367-B21, 691367-B22, 648311-B21, 648312-B21, 737685-B21, 787635-
			B22, C8S45A, C8S46A, C8S47A.
		Removed	Obsolete SKUs were deleted:
			E5Y41AAE, 498358-B21, 410916-B21, 451438-B21, 451439-B21, 641016-
			B21.
30-May-2016	From Version17 to 18	Changed	Sections in QuickSpecs were updated.
19-Jul-2013	From Version 16 to 17	Changed	HPE Power Advisor was added and HPE BladeSystem Power Sizer was
			removed from HPE BladeSystem c-Class Overview
			Steps 2, 3, 5, and 6 were revised in Storage
			Acoustic Noise was revised in Power
12-Jul-2013	From Version 15 to 16	Changed	Storage: Updated Step 5, HPE BladeSystem c-Class Network
			Interconnects section.
06-May-2013	From Version 14 to 15	Changed	Storage: Updated Step 5, HPE BladeSystem c-Class Network
			Interconnects section.
05-Apr-2013	From Version 13 to 14	Changed	Storage: Updated Note in Step 2, Updated HPE BladeSystem c-Class
			Network interconnects and HPE BladeSystem c-Class SAN Interconnect
			sections in Step 5, completely Updated Step 6 and updated Rack Options
			for HPE Seismic Rack.
06-Jan-2012	From Version 12 to 13	Added	HPE Virtual Connect FlexFabric 10GB/24-port Module for c-Class
			BladeSystem was added to HPE BladeSystem c-Class Network
			Interconnects
			HPE NC532m Dual Port 10GbE Multifunction BL-c Adapter, HPE
			NC550m 10Gb 2-port PCIe x8 Flex-10 Ethernet Adapter, HPE NC551m
			Dual Port FlexFabric 10Gb Converged Network Adapter and HPE
			NC553m 10Gb 2-port FlexFabric Adapter were added to Mezzanine
			Options
			HPE 600GB 6G SAS 10K SFF DP ENT HDD, HPE 450GB 6G SAS 10K SFF
			DP ENT HDD and HPE 120GB 3G SATA SFF (2.5 inch) ENT Perf 3yr
			Warranty Solid State Drive were added to Hard Drives
29-Jul-2011	From Version 11 to 12	Changed	HPE BladeSystem c-Class Network Interconnects was revised in Step 5
			and HPE BL460c G6 was revised in Step 6.
23-Mar-2011	From Version 10 to 11	Changed	Correction made to two part numbers in Step 6.
28-Jan-2011	From Version 9 to 10	Removed	Removed part number 572018-B21 from Step 5 of the Storage section.
13-Aug-2010	From Version 8 to 9	Changed	Changes made in the Storage and Technical Specifications sections.
26-Jul-2010	From Version 7 to 8	Changed	Description and part number changes made in the interconnect section.
14-May-2010	From Version 6 to 7	Changed	Changes made within the Overview, Storage and Technical Specifications
			sections.

QuickSpecs

Summary of Changes

16-Apr-2010	From Version 5 to 6	Changed	Part number was changed for HPE -48VDC 30 amp breaker for AH335A
			in Rack Options for HPE Seismic Rack.
02-Apr-2010	From Version 4 to 5	Removed	Removed part number 399593-B22 from Step 5.
05-Feb-2010	From Version 3 to 4	Added	Added the NC382m to the tested NICs list.
05-Jan-2010	From Version 2 to 3	Changed	Corrected the description for part number 455880-B21 in Step 5.



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